

SAN DIEGO, CA – September 17, 2024 – Chiplet Summit 2024 Shows How Advanced Packaging Keeps Moore’s Law Alive

Smaller design nodes are now far more costly and much harder to achieve. So interest has turned to approaches that do more at the package level. Chiplet Summit helps educate both design and packaging engineers. The advanced packaging tutorial covers methods such as 3D, wafer-scale, and panel-scale. The Working with Foundries tutorial then shows how such approaches have become part of manufacturing. Later sessions deal with finding the right package for an application, as well as short-term and long-term trends.

The Summit also offers major company keynotes, expert tables, panels, and paper sessions. An exhibit hall has key products from industry leaders.

“Chiplet Summit helps designers profit from major advances in packaging,” said Chuck Sobey, Summit General Chair. “Designers and packagers can both learn how to develop SiPs (systems-in-package), use die-to-die interfaces such as UCle, and create supercomputers in a package.”

To discuss exhibiting, contact:

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About Chiplet Summit

Chiplet Summit, produced by Semper Technologies, showcases the applications, technologies, and leading vendors that drive the growing chiplet market.

To learn more about the Summit, visit <https://chipletsummit.com>.

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